

Product Description

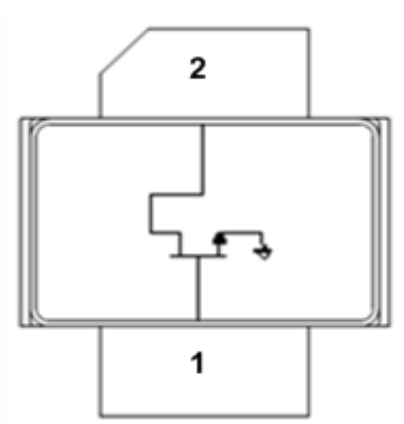
The QPD2195 is a discrete GaN on SiC HEMT which operates from 1.8-2.2 GHz. The device is a single stage pre-matched power amplifier transistor.

The QPD2195 can be used in Doherty architecture for the final stage of a base station power amplifier for macrocell high efficiency systems.

QPD2195 can deliver P_{3dB} of 400 W at +48 V operation.

Lead-free and ROHS compliant.

Functional Block Diagram



2 Lead NI780 Package

Product Features¹

- Operating Frequency Range: 1.8-2.2 GHz
- Operating Drain Voltage: +48 V
- Maximum Output Power¹ (P_{3dB}): 400 W
- Maximum Drain Efficiency¹: 75.4%
- Efficiency-Tuned P3dB Gain¹: 19.1 dB
- 2-lead, earless, ceramic flange NI780 package

Note 1: @ 2.11 GHz Load Pull

Applications

- W-CDMA / LTE
- Macrocell Base Station, B3-B1
- Active Antenna

Ordering Information

Part No.	ECCN	Description
QPD2195S2	EAR99	Box (2 Samples Each)
QPD2195SQ	EAR99	Tray (25 Samples)
QPD2195SR	EAR99	Reel (100 Samples)
QPD2195PCB4B01	EAR99	1.805-2.170 GHz Eval. Board



QPD2195

400 W, 48 V, 1.8-2.2 GHz GaN RF Power Transistor

Absolute Maximum Ratings

Parameter	Value / Range
Gate Current (I_G)	-67 to 67 mA
Drain Voltage (V_D)	+55 V
Peak RF Input Power	44 dBm
VSWR Mismatch, P1dB Pulse (10 % duty cycle, 100 μ width), T = 25 °C	10:1
Storage Temperature	-65 to +150°C

Operation of this device outside the parameter ranges given above may cause permanent damage.

Recommended Operating

Parameter	Min	Typ	Max	Units
Operating Temperature	-40	-	-	°C
Gate Voltage (V_G)	-	-2.8	-	V
Drain Voltage (V_D)	-	48	-	V
Quiescent Current (I_{DQ})	-	720	-	mA
T_{CH} for >10 ⁶ hours MTTF	-	-	250	°C

Electrical performance is measured under conditions noted in the electrical specifications table. Specifications are not guaranteed over all recommended operating conditions.

RF Characterization

Parameter	Conditions	Min	Typ	Max	Units
Frequency Range		1805	-	2170	MHz
Quiescent Current		-	720	-	mA
Linear Gain		-	20.4	-	dB
P3dB		-	56.3	-	dBm
Drain Efficiency	P3dB	-	70.1	-	%

Test conditions unless otherwise noted: $V_D = +48$ V, $I_{DQ} = 720$ mA, T = 25°C, Pulsed CW (10% duty cycle, 100 μ s width) on Class AB single-ended EVB at 1880 MHz

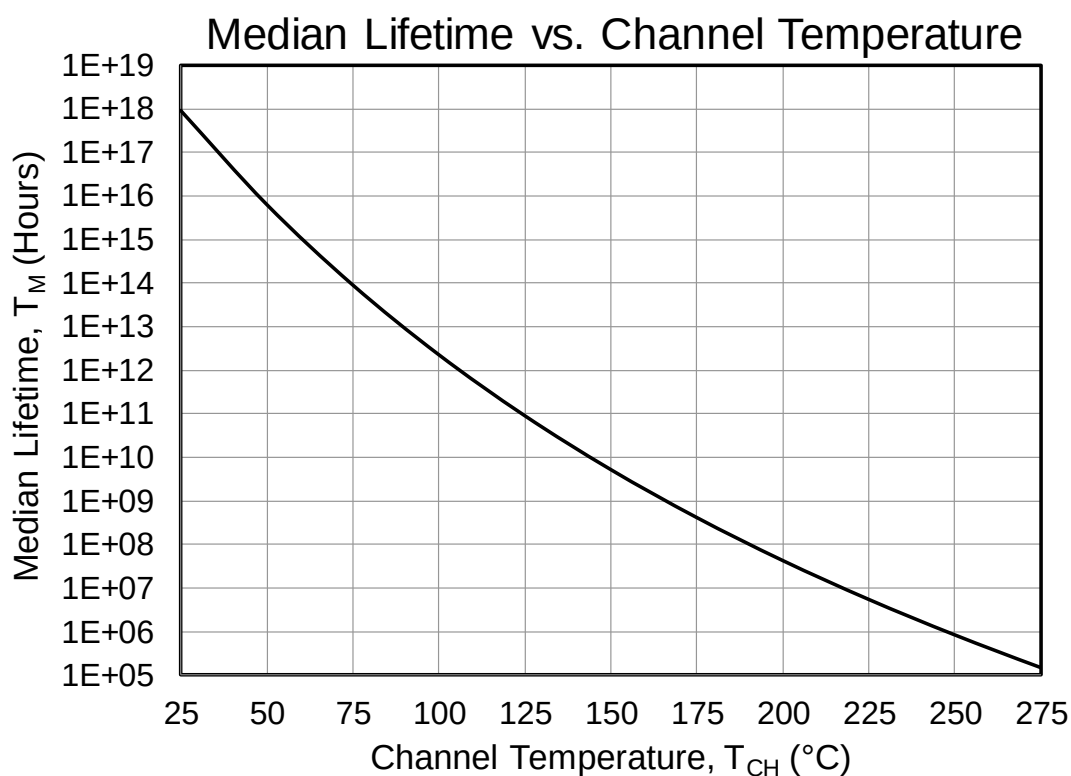
Thermal and Reliability Information

Parameter	Test Conditions	Value	Units
Carrier Amplifier Thermal Resistance at Average Power (θ_{JC})	$T_{CASE} = 85^{\circ}\text{C}$, $T_{CH} = 121^{\circ}\text{C}$, CW: $P_{DISS} = 60\text{ W}$, $P_{OUT} = 90\text{ W}$	0.6	$^{\circ}\text{C/W}$

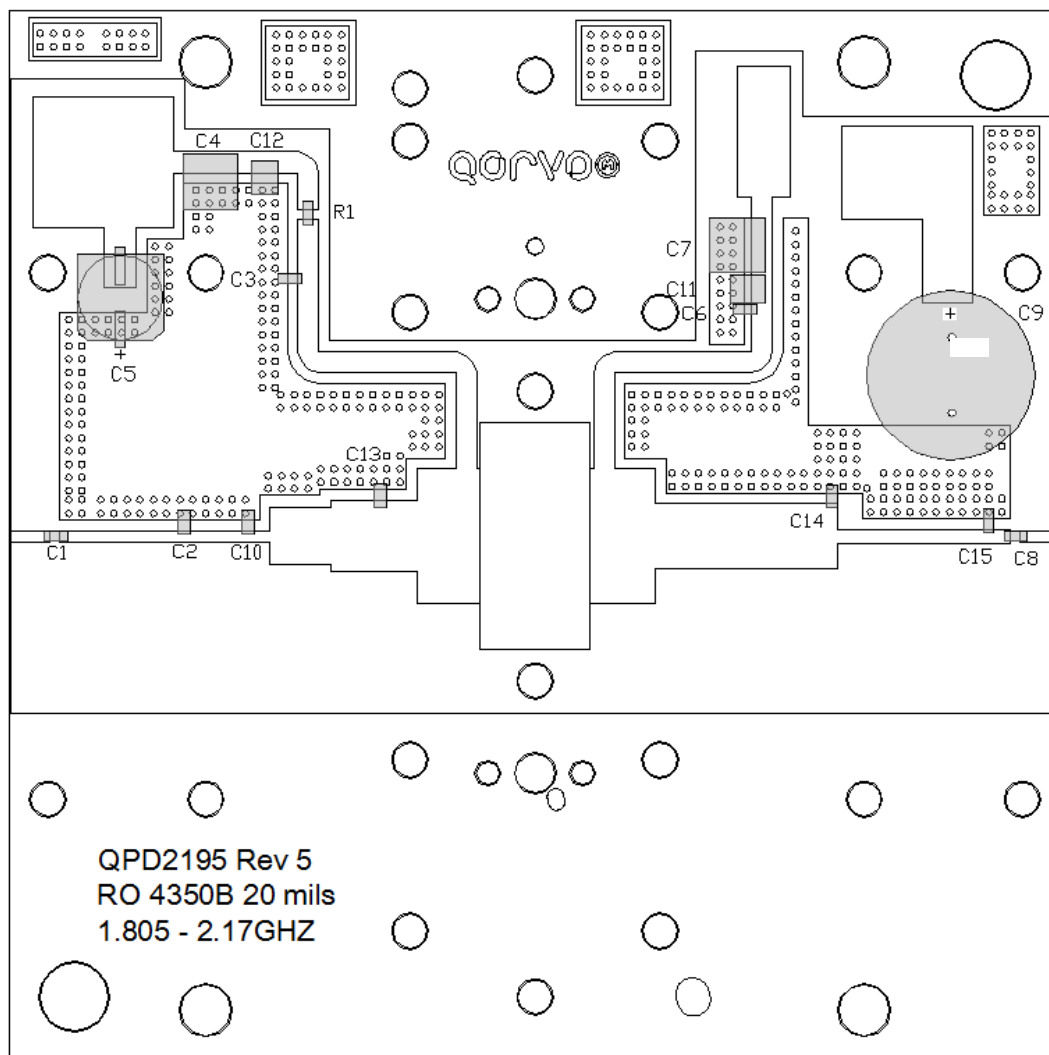
Notes:

1. Thermal resistance measured to package backside.
2. Based on expected carrier amplifier efficiency of Doherty.
3. P_{OUT} assumes 20% peaking amplifier contribution of total average Doherty rated power.

Median Lifetime



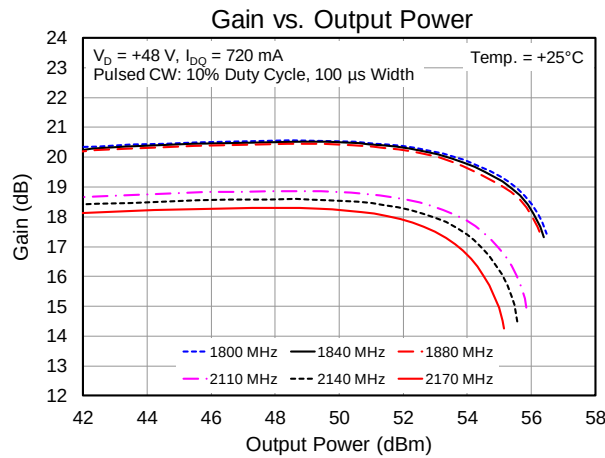
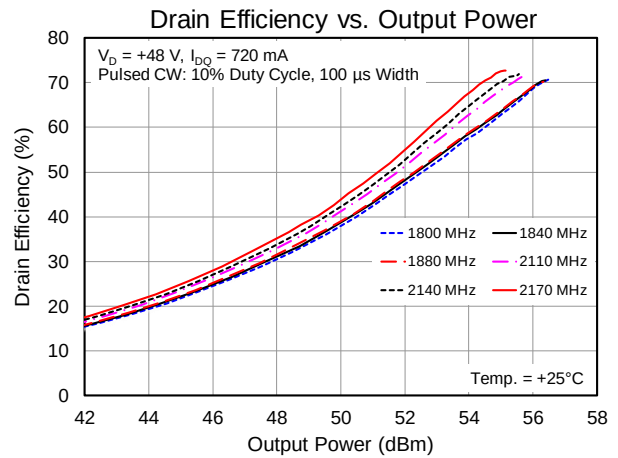
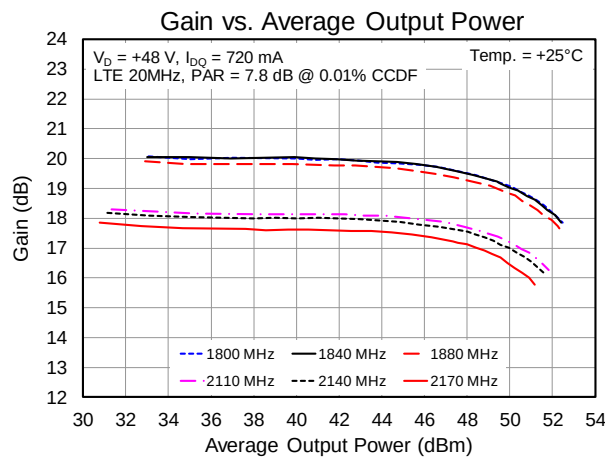
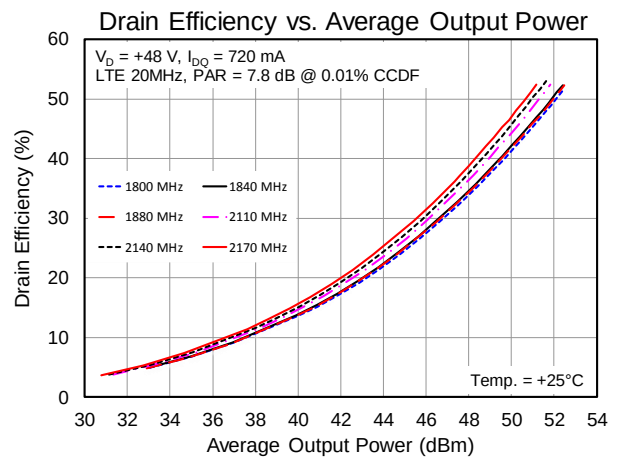
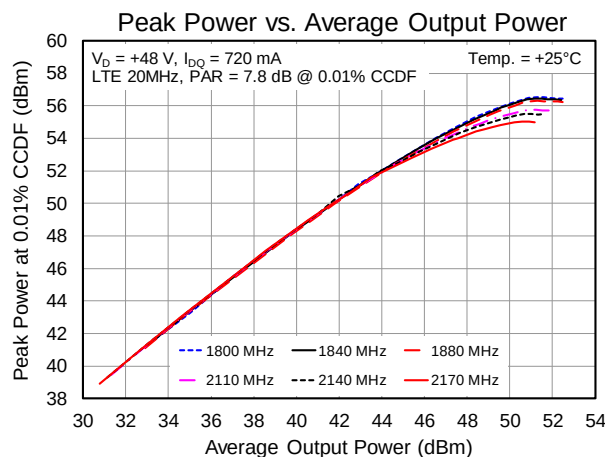
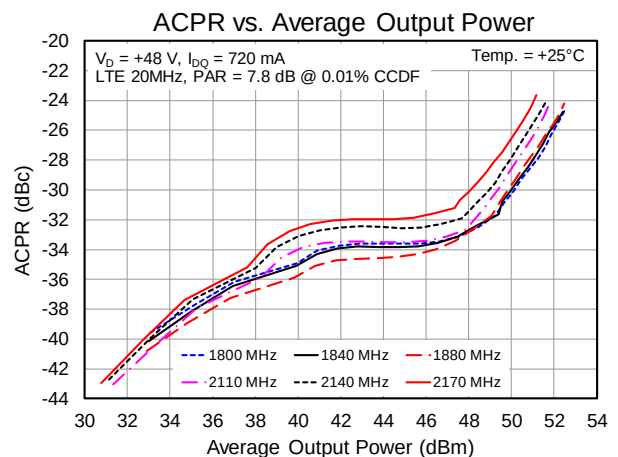
Single-Ended Evaluation Board Layout



Bill of Materials

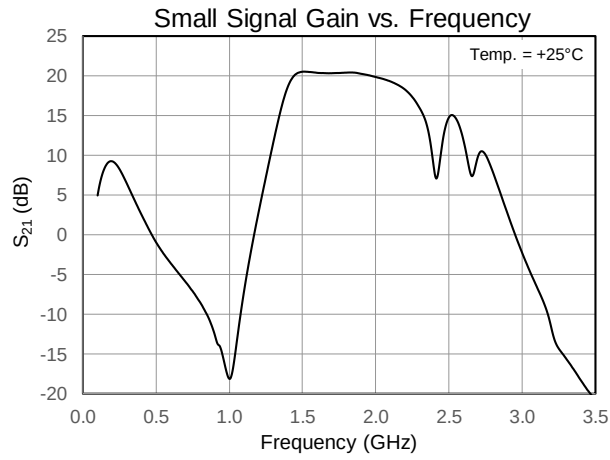
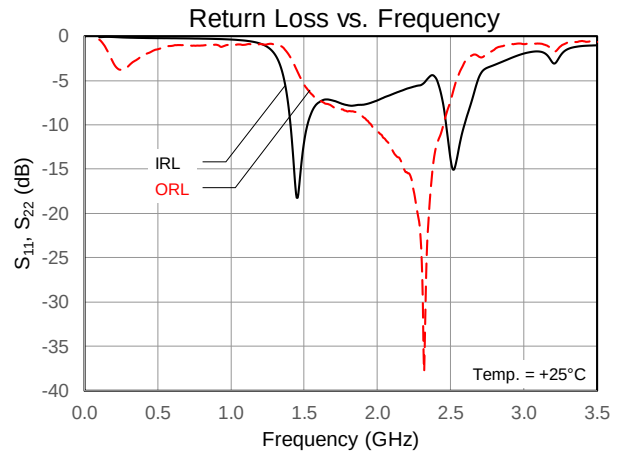
Reference Des.	Value	Description	Manuf.	Part Number
C1, C3, C6, C8	33 pF	Capacitor, 33 pF, 5%, 250V	ATC	ATC800A330JT250X
C2	0.6 pF	Capacitor, 0.6 pF, +/- 0.1pF, 250V	ATC	ATC800A0R6BT250X
C10	0.2 pF	Capacitor, 0.2 pF, +/- 0.1pF, 250V	ATC	ATC800A0R2BT250X
C14, C15	0.4 pF	Capacitor, 0.4 pF, +/- 0.1pF, 250V	ATC	ATC800A0R4BT250X
C13	0.3 pF	Capacitor, 0.3 pF, +/- 0.1pF, 250V	ATC	ATC800A0R3BT250X
C11, C12	1.0 μ F	Capacitor, 1 μ F, 10%, 100V, X7R	MURATA	GRM32NR72A104KA01L
C4, C7	4.7 μ F	Capacitor, 4.7 μ F, 10%, 100V, X7R	MURATA	GRM55ER72A475KA01L
C5	100 μ F	Capacitor, 100uF, 50V, +/-20%, SMD	Panasonic	EEE-1HA101UAP
C9	220 μ F	Capacitor, 220uF, 100V, +/-20%, SMD	Panasonic	AFK227M2AR44T-F
R1	10 Ω	Resistor, 10 Ω , 5%, 0.25W, 1206	Panasonic	ERJ-8ENF10R0V

Single-Ended Evaluation Board Performance Plots



Test conditions unless otherwise noted: $V_D = +48\text{ V}$, $I_{DQ} = 720\text{ mA}$, $T = 25^\circ\text{C}$, on Class AB single-ended EVB

Single-Ended Evaluation Board Performance Plots



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400 W, 48 V, 1.8-2.2 GHz GaN RF Power Transistor

RF Characterization – Power-Tuned Load Pull Performance

Frequency (MHz)	Source Impedance	Load Impedance	Gain @ P3dB (dB)	P3dB (dBm)	Drain Efficiency (%)
1800	1.68 – j2.21	5.39 – j1.33	18.2	56.0	60.5
1840	1.34 – j2.45	5.39 – j1.33	18.1	56.1	62.7
1880	1.44 - j2.82	5.54 - j0.11	17.8	56.2	60.9
1990	1.51 – j3.72	5.79 + j1.48	17.4	56.0	60.4
2110	2.00 – j5.57	3.89 + j3.09	17.2	56.0	60.5
2140	2.48 – j6.14	3.67 + j3.42	16.7	56.0	59.5
2170	3.07 - j6.71	3.67 + j3.42	16.6	56.1	61.8
2200	3.38 – j7.21	3.11 + j3.04	16.6	55.9	58.5

Test conditions unless otherwise noted: $V_D = +48$ V, $I_{DQ} = 720$ mA, $T = 25^\circ\text{C}$, Pulsed (10% duty cycle, 100 μs width)

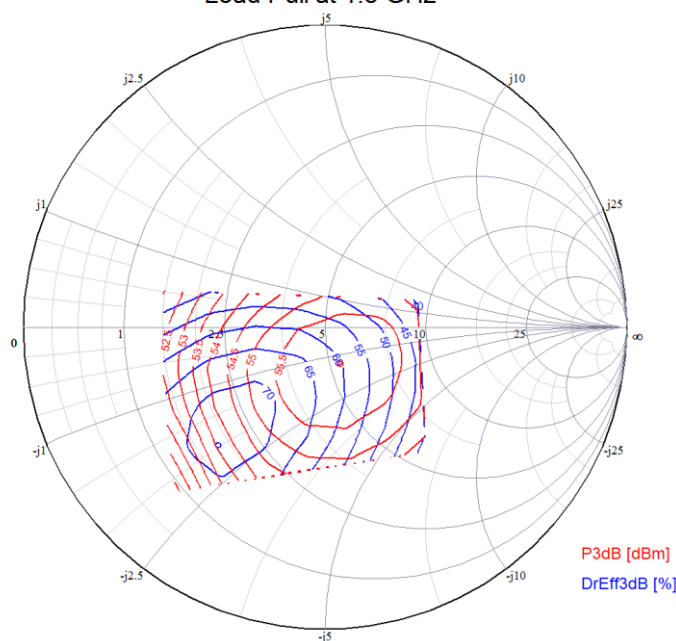
RF Characterization – Efficiency-Tuned Load Pull Performance

Frequency (MHz)	Source Impedance	Load Impedance	Gain @ P3dB (dB)	P3dB (dBm)	Drain Efficiency (%)
1800	1.68 – j2.21	1.79 – j1.97	20.3	53.5	72.6
1840	1.34 – j2.45	1.79 – j1.97	20.2	53.2	73.3
1880	1.44 - j2.82	1.79 - j1.97	19.9	53.1	73.9
1990	1.51 – j3.72	3.10 – j1.88	19.4	53.9	74.1
2110	2.00 – j5.57	4.36 – j2.15	19.1	53.2	75.4
2140	2.48 – j6.14	4.40 – j2.03	18.8	53.0	75.5
2170	3.07 - j6.71	5.70 - j2.55	18.4	53.0	77.4
2200	3.38 – j7.21	6.74 – j1.27	18.4	53.6	75.5

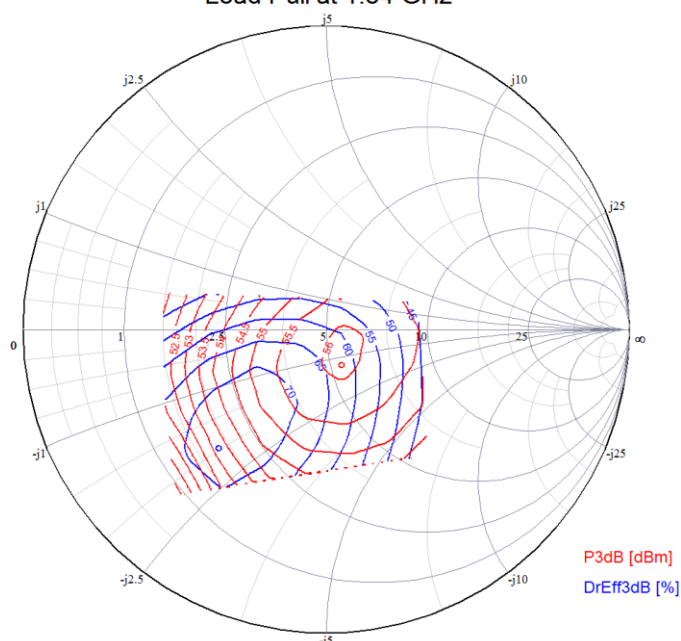
Test conditions unless otherwise noted: $V_D = +48$ V, $I_{DQ} = 720$ mA, $T = 25^\circ\text{C}$, Pulsed (10% duty cycle, 100 μs width)

Load Pull Plots

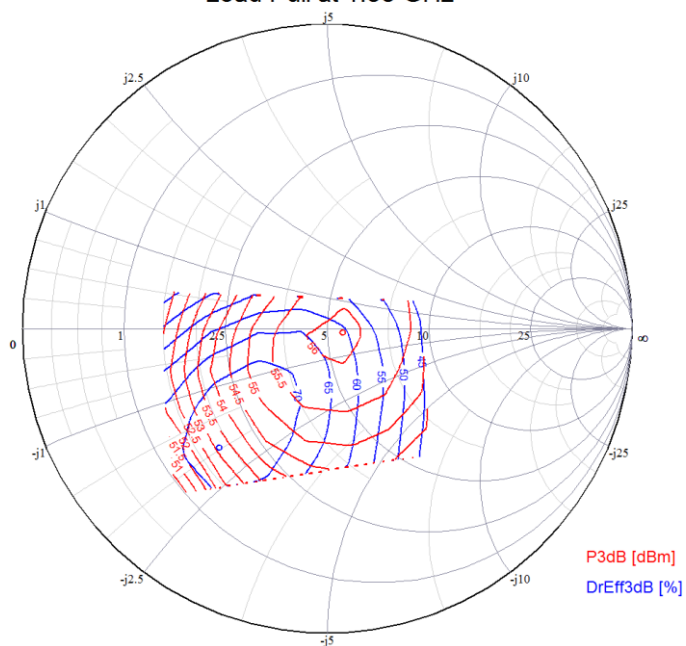
Load Pull at 1.8 GHz



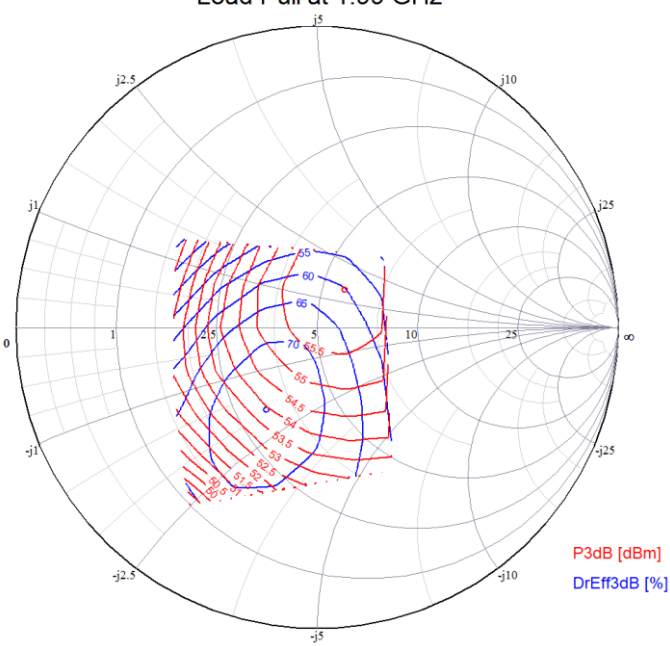
Load Pull at 1.84 GHz



Load Pull at 1.88 GHz

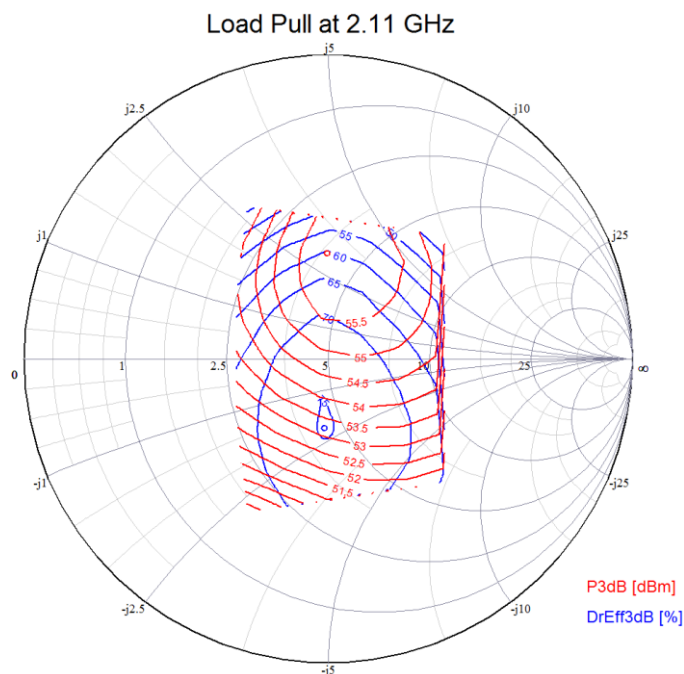
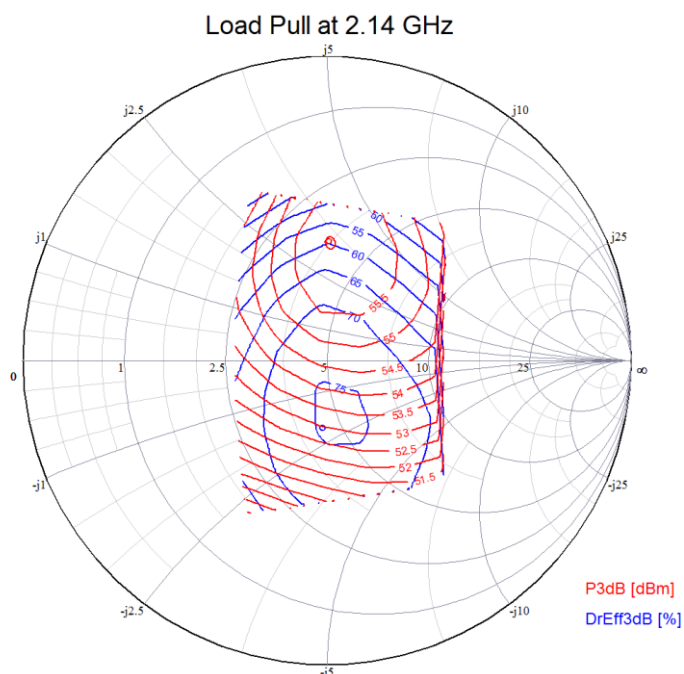
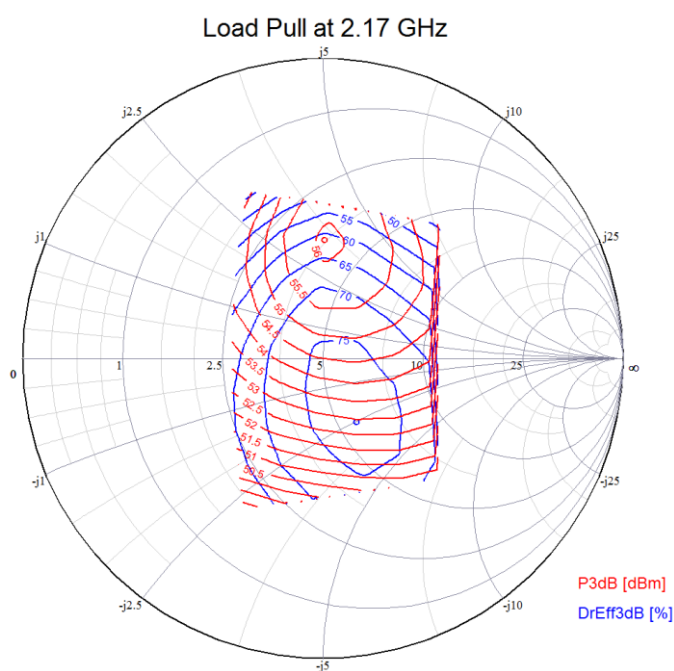
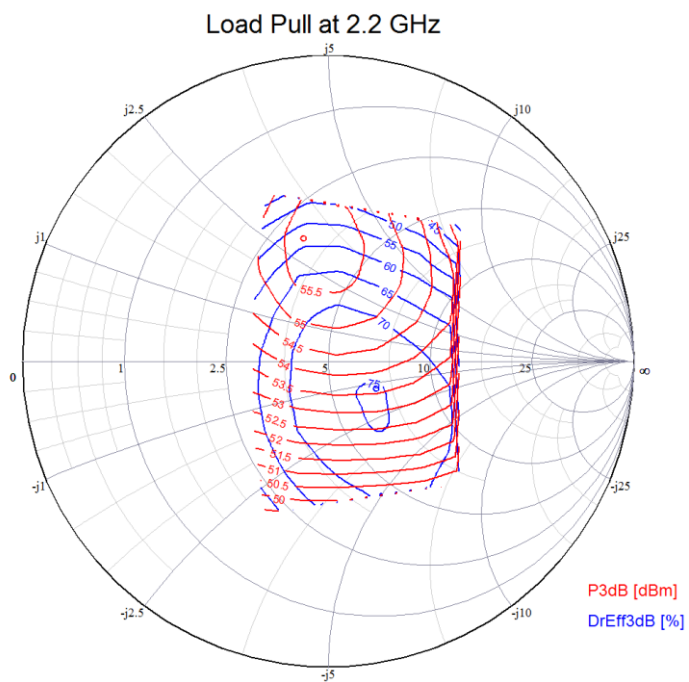


Load Pull at 1.99 GHz



Test conditions unless otherwise noted: $V_D = +48$ V, $I_{DQ} = 720$ mA, $T = 25^\circ\text{C}$, Pulsed (10% duty cycle, 100 μs width)

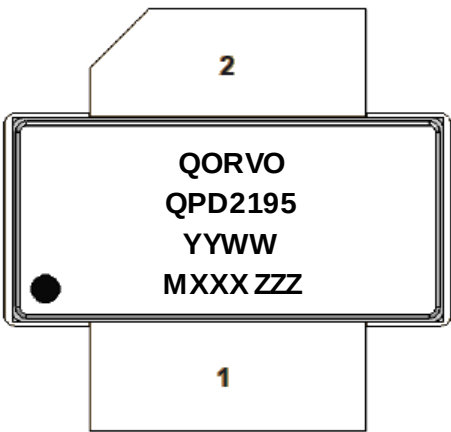
Load Pull Plots



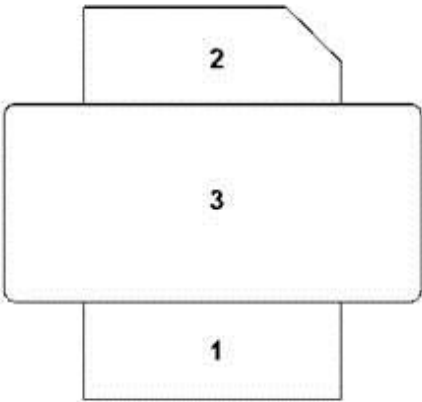
Test conditions unless otherwise noted: $V_D = +48$ V, $I_{DQ} = 720$ mA, $T = 25^\circ\text{C}$, Pulsed (10% duty cycle, 100 μs width)



Pin Configuration



TOP VIEW



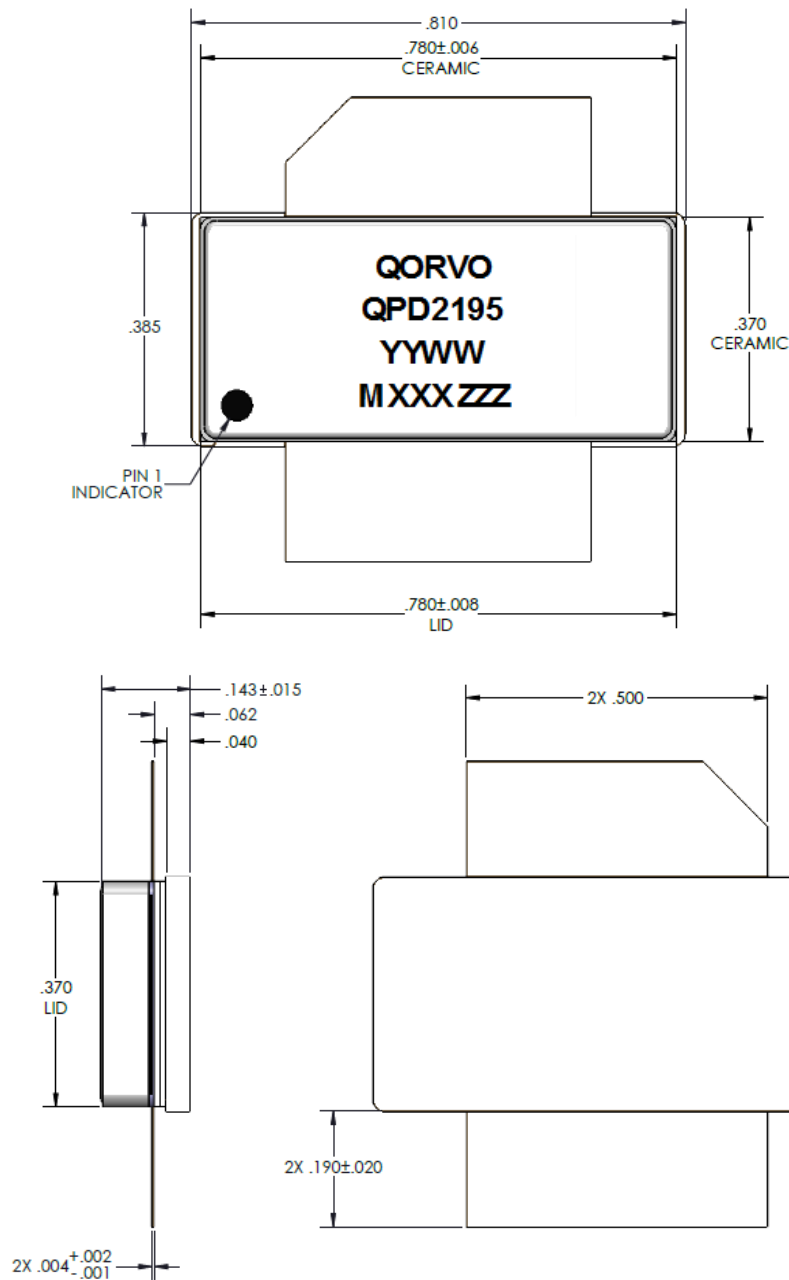
BOTTOM VIEW

Pin Description

Pin No.	Label	Description
1	RF IN, VG	RF Input, Gate Bias
2	RF OUT, VD	RF Output, Drain Bias
3 (Backside Paddle)	RF/DC GND	RF/DC Ground

Package Marking and Dimensions

Marking: Qorvo Logo
 Part Number and Package Version – QPD2195
 Date Code – YYWW
 Production Lot Number – MXXX
 Serial Number – ZZZ



Notes:

1. All dimensions are in inches. Angles are in degrees.
2. Exposed metallization is NiAu plated.



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Handling Precautions

Parameter	Rating	Standard
ESD – Human Body Model (HBM)	Class 1B	JEDEC Standard JESD22 A114
ESD – Charged Device Model (CDM)	TBD	JEDEC Standard JESD22-C101F
MSL – 260°C Convection Reflow	Level 3	JEDEC standard IPC/JEDEC J-STD-020.



Caution!
ESD-Sensitive Device

Solderability

Compatible with both lead-free (260°C maximum reflow temperature) and tin/lead (245 °C maximum reflow temperature) soldering processes.

The use of no-clean solder to avoid washing after soldering is recommended.

Contact plating: NiAu

RoHS Compliance

This product is compliant with the 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment), as amended by Directive 2015/863/EU. This product also has the following attributes:

- Lead Free
- Antimony Free
- TBBP-A (C₁₅H₁₂Br₄O₂) Free
- PFOS Free
- SVHC Free

Contact Information

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